



16th Pisa Meeting on Advanced Detectors

# ALLEGRO FCC-ee detector concept & R&D on noble-liquid calorimetry

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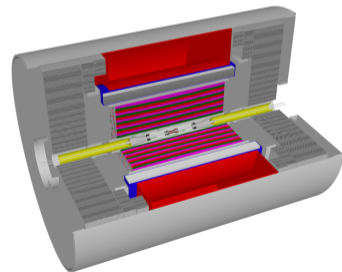
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CERN



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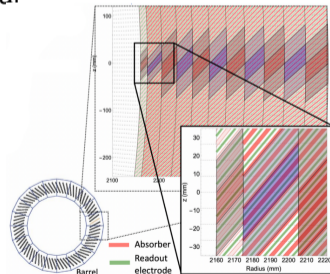
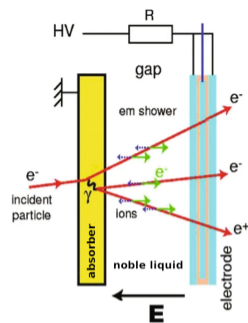
# ALLEGRO detector concept

- ▶ Proposed general-purpose detector for FCC-ee
- ▶ Recently coined as ALLEGRO
  - A Lepton-Lepton collider Experiment with Granular Read-Out
- ▶ High-granularity noble-liquid ECAL a central and most studied feature
  - LAr or LKr as active medium, Pb or W absorbers
  - Multi-layer PCB as readout electrode
- ▶ Vtx detector, drift chamber and ECAL inside 2 T solenoid magnet, sharing cryostat
- ▶ HCAL and muon system outside solenoid
- ▶ Optimized for full FCC-ee physics program
  - Focus on PFlow & particle ID performance



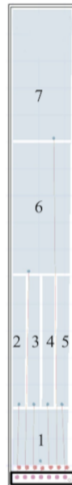
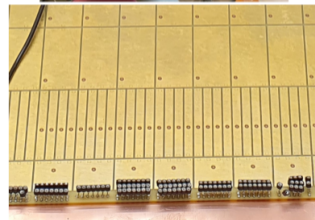
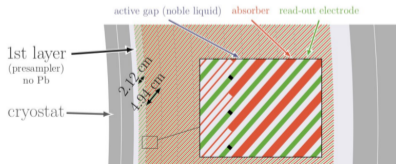
# Noble-liquid calorimetry

- ▶ Sampling calorimetry relying on ionization of active material (liquefied noble gas)
- ▶ Based on alternating layers of absorbers, noble liquid and readout electrodes
  - Voltage applied over noble-liquid gap
  - Incident particle ionizes noble liquid
  - $e^-$  (and ions) drift to electrodes and induce current signal
- ▶ Successful in many HEP experiments
  - MarkII, DØ  , H1, NA48/62, ATLAS 
- ▶ Advantages: excellent energy resolution, linearity, stability and uniformity, good timing properties
- ▶ Challenges: complex mechanical structure inside cryostat, granularity



# High-granularity noble-liquid calorimeter

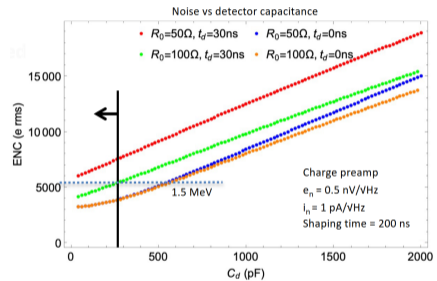
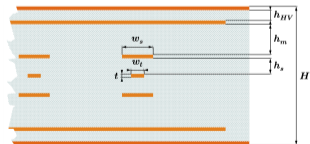
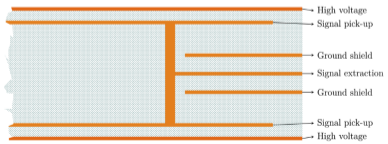
- ▶ Printed circuit board (PCB) technology allows "arbitrarily" high granularity
  - Signal traces inside the electrode
  - Target: at least 10x ATLAS granularity
- ▶ CERN prototype PCB 58 cm × 44 cm →
  - 50° inclination, gives 40 cm (22  $\chi_0$ ) thick ECAL
  - Split to 16  $\theta$ -towers & 12 depth layers; 240 cells
  - Narrow strips in front for  $\pi^0$  detection
  - 7-layer PCB, complex internal structure
  - Readout from inner and outer edge
- ▶ New PCB with outer edge readout & other updates to be produced shortly

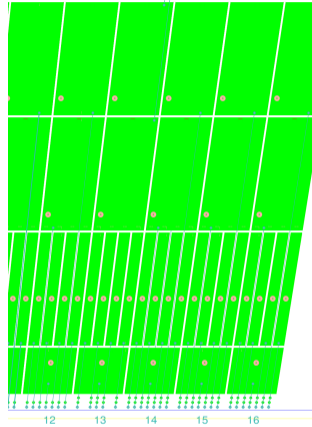
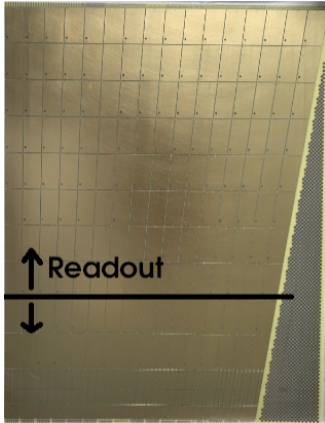




# Readout electrode structure & shielding

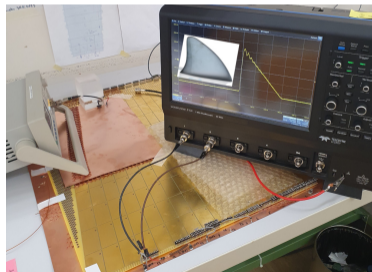
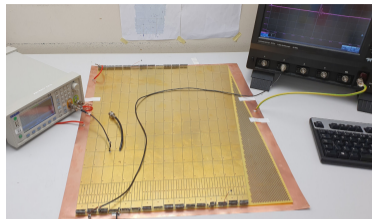
- ▶ Signal traversing under other cells induces *cross-talk* (x-talk) that worsens resolution
- ▶ Can be mitigated by sandwiching signal traces between grounded shields
- ▶ **Trade-off between x-talk and electronics noise**
  - Shields reduce x-talk but increase capacitance to ground and hence noise
- ▶ In PCB v0 baseline is 2x width shields above and below each signal trace
  - Other configurations implemented for studies



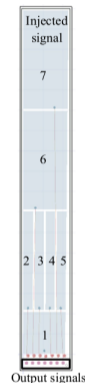
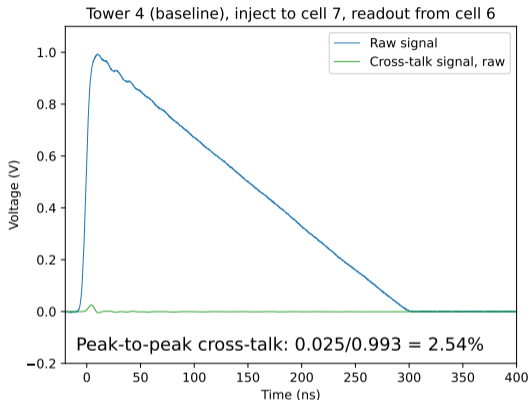


# PCB measurement setup

- ▶ Electrical properties measured with a table-top setup
- ▶ Copper sheet as grounding and "absorbers" above and below the electrode
- ▶ Function generator used for injecting shark-fin signal
  - 300 ns wide 1 V peak at 5 ms intervals
  - Mimics the real signal of drifting charges
- ▶ Main and x-talk signal read with oscilloscope and analyzed offline
- ▶ Extra care needed for good quality measurements
  - Short cables, thorough grounding, impedance matching

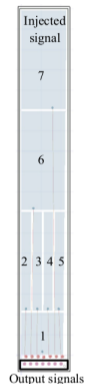
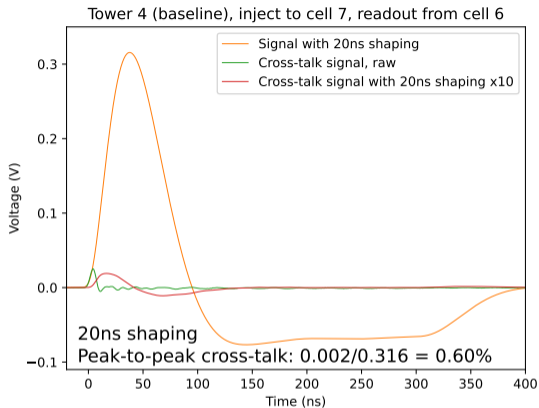


# PCB measurements



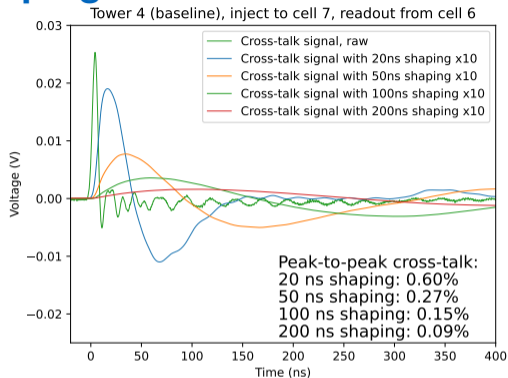
- ▶ Compare main signal magnitude to x-talk signal
- ▶ X-talk measured as "peak-to-peak" ratio
- ▶ X-talk ratio of <1% is needed and achieved with *shaping*

# PCB measurements



- ▶ Signals shaped with ATLAS-style CR-RC<sup>2</sup> shaper
  - Here modeled by an analytical function
  - In reality implemented with electronics
- ▶ After shaping x-talk signal too small to see → ×10

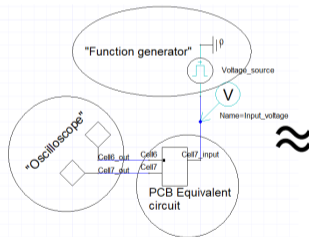
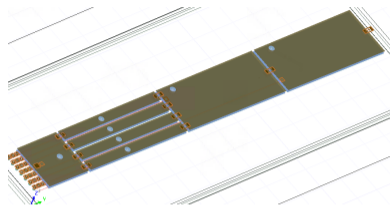
# Cross-talk and shaping time



- ▶ Longer shaping time gives lower x-talk
  - At LHC long shaping times not good due to pileup, but fine in  $e^+e^-$
- ▶ X-talk down to 0.1% and less with long shaping time
  - Also noise goes down with longer shaping time
- ▶ Low x-talk seen also in other shielding configurations

# Readout electrode simulation studies

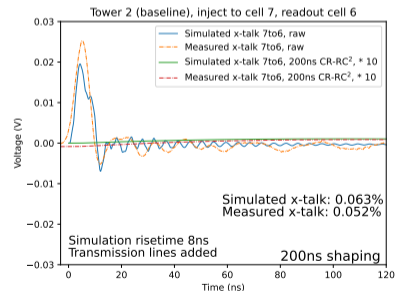
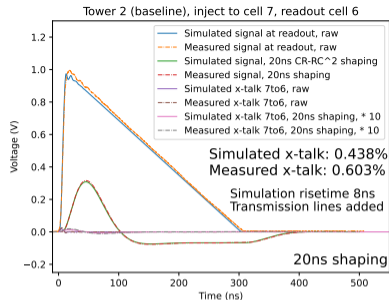
- ▶ Electrode properties also studied with simulations
  - Using Ansys Electronics Desktop
- ▶ A cut-out of the PCB taken and prepared to equivalent configuration as in the lab
  - Same conductor & dielectric materials, grounding, absorbers, input & output ports
- ▶ Model analyzed and converted to equivalent circuit, results analyzed





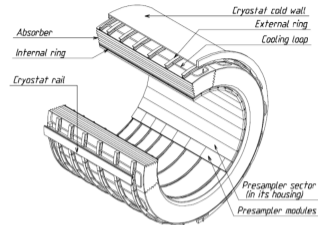
# PCB simulation studies

- ▶ Main signal and x-talk signal shapes in good agreement with measurements
  - Accounting for the finite turn-on of the analog signal
- ▶ X-talk in the same ballpark with 20 ns shaping
  - Exact replication of laboratory setup hard to achieve
  - With 200 ns shaping time x-talk values agree well
- ▶ Agreement sufficient for starting to try new ideas with simulations
  - Different shielding scenarios (e.g. lateral shields)
  - 6-layer PCB with one-sided or alternating shields

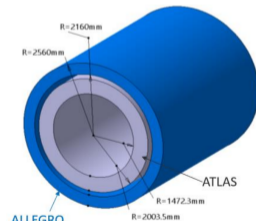
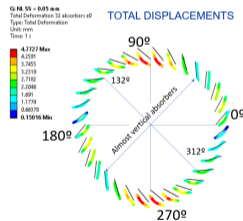
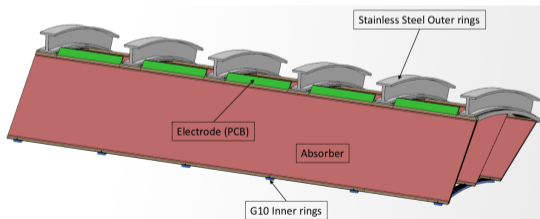


# Barrel ECAL - mechanical design

- ▶ ATLAS LAr ECAL used as reference
  - Larger radius, new electrode geometry
- ▶ Finite element analysis used for structural element design (strength, size)
- ▶ Clever solutions needed for making the structure possible to build!



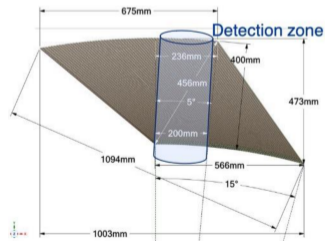
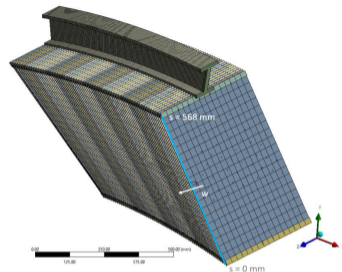
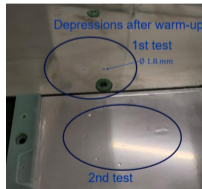
ATLAS liquid argon calorimeter general layout



ALLEGRO EM calorimeter size comparison

# Absorbers & test-beam prototype

- ▶ First absorber prototypes produced with 1.8 mm of lead with 50  $\mu\text{m}$  steel layers
- ▶ Immersed to liquid nitrogen, small depressions seen after cold test
  - Origin being investigated, thicker 100  $\mu\text{m}$  steel layer being studied
- ▶ Design of test beam prototype frozen by 9/2025
  - 64 electrodes and absorbers
  - Big enough for containing a typical shower
  - To be placed in a cryostat for beam tests

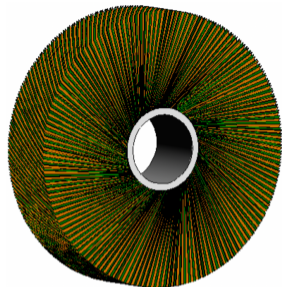
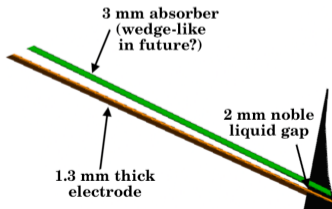


# Endcap EM calorimeter

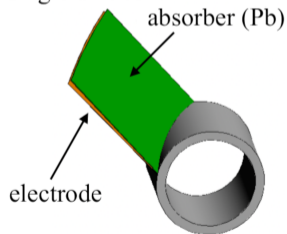
- ▶ Noble-liquid based sampling calorimeter
- ▶ ECAL endcap designed to feature:
  - Thin absorbers (high granularity)
  - Readout from outside faces only (no dead material), uniformity in  $\phi$

## ⇒ Turbine-like geometry as one option

- ▶ ~240 absorbers and electrodes each
- ▶ Geometry ported to FCC-SW for FCC-ee simulations



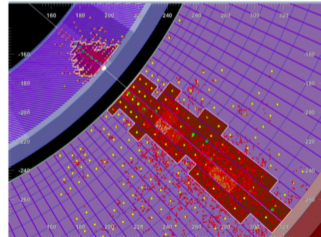
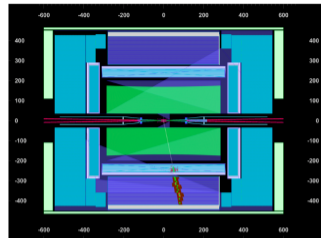
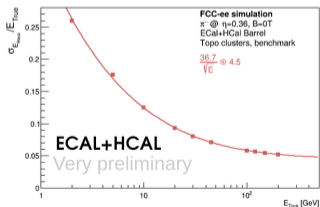
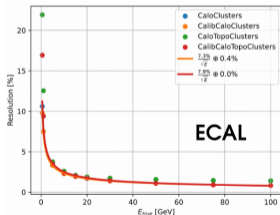
single unit cell:



drawings by Rob Walker

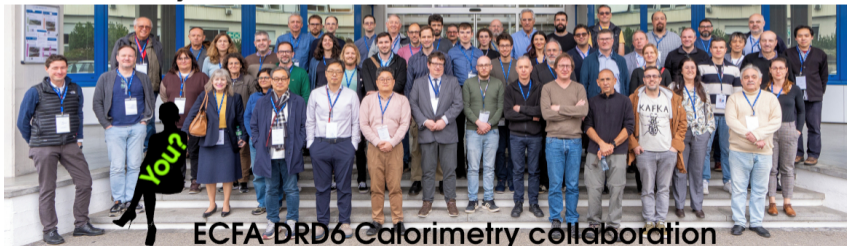
# Detector simulation & clustering

- ▶ Optimal granularity & materials being studied with simulations
  - Find optimal granularity for  $\pi^0/\gamma$  separation
  - LAr or LKr as liquid, Pb or W as absorbers
- ▶ Full-Sim of ALLEGRO being built to FCC-SW
  - ECAL+HCAL topo-clustering implemented
  - Next: add tracking and Particle Flow
- ▶ EM resolution with a sampling term of 7-8% in simulation



# Conclusions & outlook

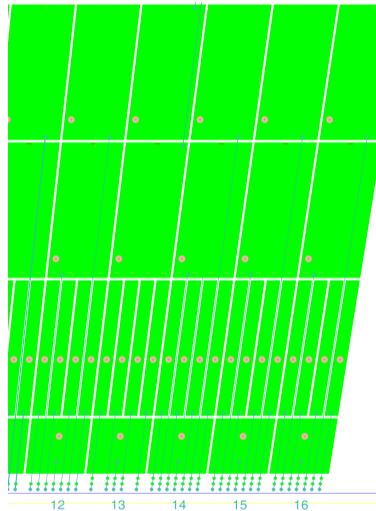
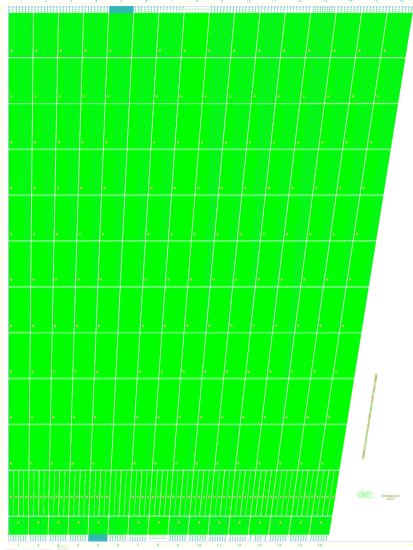
- ▶ ALLEGRO is a general-purpose FCC-ee detector concept
- ▶ Multi-layer PCB's as readout electrodes allow high granularity
- ▶ New prototype PCB being designed at CERN
- ▶ Test-beam prototype to be built by 2027-28
  - To be studied with test beams inside a cryostat
- ▶ ECFA DRD6 Calorimetry collaboration founded in April
  - Noble-liquid calorimetry in work package 2
- ▶ Team is growing fast, already 20 institutions joined!
  - **Ideal time to join ALLEGRO!**

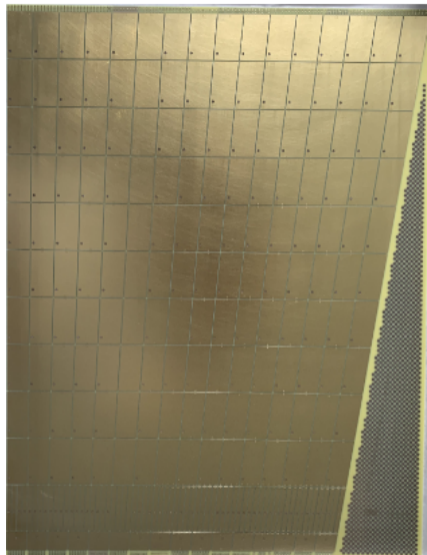
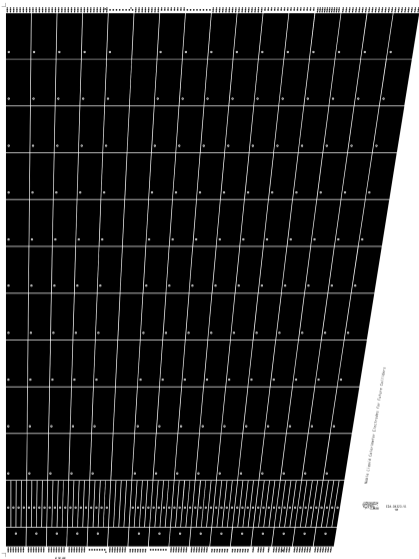


# Back-up







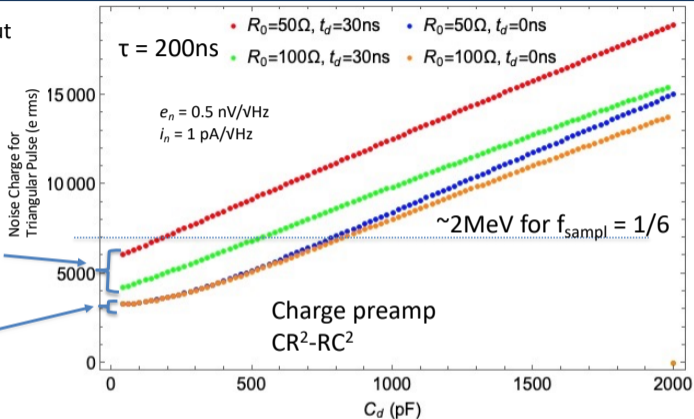


# Noise as a Function of $C_d$ and Impedance $R_0$

Series noise ENC scales with  $C_d$ , but parallel noise (independent of  $C_d$ ) becomes dominant for small  $C_d$ .

Total noise including 5m transmission line ( $t_d = 30$  ns)

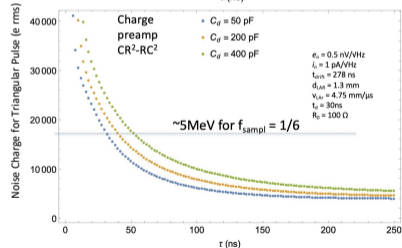
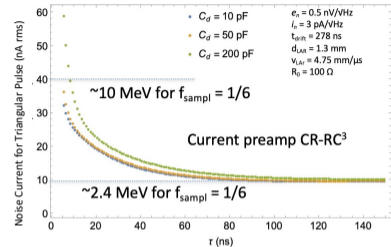
Total noise without transmission line ( $t_d = 0$  ns)



Adding a transmission line (here 5m,  $t_d = 30$  ns) leads to **deterioration of noise**  
Higher impedance ( $50 \Omega \rightarrow 100 \Omega$ ) **reduces effect** of transmission line.

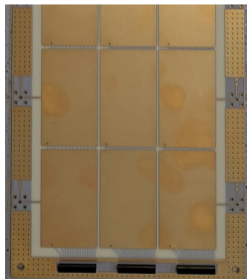
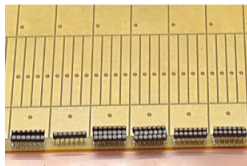
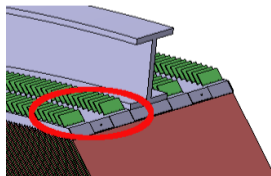
# Optimizing the Noise Level

- Assume transmission line of 5 m ( $t_d = 30$  ns)
- $R_0 = 100 \Omega$  is supposed to be the highest possible impedance for the coax cables leading the signal out (e.g. [Axon](#))
  - difficult to obtain for transmission line inside the PCB
- **Current preamp (CR-RC<sup>3</sup>), see plot:**
  - $e_n = 0.5$  nV/VHz and  $i_n = 3$  pA/VHz
  - Achieving **2.4 MeV noise** for  $\tau > 80$  ns and  $R_0 = 100 \Omega$
  - Achieving **3.0 MeV noise** for  $\tau > 100$  ns and  $R_0 = 50 \Omega$
- **Charge preamp (CR<sup>2</sup>-RC<sup>2</sup>)** generally show lower parallel noise  $i_n$ :
  - e.g.  $e_n = 0.5$  nV/VHz and  $i_n = 1$  pA/VHz
  - Achieving **1.3 MeV noise** for  $\tau = 200$  ns,  $C_d = 100$  pF and  $R_0 = 100 \Omega$
  - Achieving **1.4 MeV noise** for  $\tau = 200$  ns,  $C_d = 200$  pF and  $R_0 = 100 \Omega$
  - Achieving **1.8 MeV noise** for  $\tau = 200$  ns,  $C_d = 100$  pF and  $R_0 = 50 \Omega$
  - Achieving **1.9 MeV noise** for  $\tau = 100$  ns,  $C_d = 100$  pF and  $R_0 = 100 \Omega$
- **Only small dependence on  $C_d$**

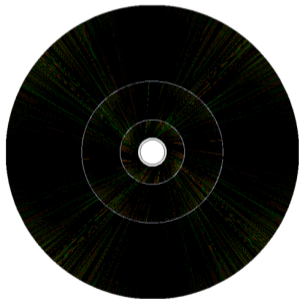


# Plans for next PCB prototype

- ▶ Simulation studies underway for optimizing granularity
- ▶ Readout from outer edge only for minimizing dead material
  - X-talk of strip layer a challenge due to smaller signal
  - Singnal traces need to be "funneled" thru support structure
  - readout pins become tiny
- ▶ Would only one shield per signal strip be sufficient?
  - 6-layer PCB easier to manufacture and thinner → increased sampling ratio
- ▶ Need to re-design readout connections
  - Industry standard connector?
  - Soon results from Paris prototype ⇒



- Another consideration is the variation of the gap with radius
  - means that response is very different at the inner and outer radii (41 cm and 275 cm)
- To mitigate this, the detector can be subdivided into a set of nested cylinders:



Tradeoff between minimizing variation in gap width vs. minimizing transitions/dead areas

In this example, each cylinder has  $r_o/r_i \approx 1.9$

